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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **OZAKI, Takashi, et al.**

Attention: **Applications Division**

Serial Number: **10/517,765**

Group Art Unit: **2812**

Filed: **February 3, 2006**

P.T.O. Confirmation No.: 6791

For: **SUBSTRATE TREATING APPARATUS AND METHOD FOR
MANUFACTURING SEMICONDUCTOR DEVICE**

REQUEST FOR CORRECTED FILING RECEIPT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Date: August 11, 2006

Sir:

Please supply the undersigned attorney with a corrected filing receipt for the above-identified application. The undersigned also respectfully requests that the Patent and Trademark Office records be amended to reflect the correction.

In reviewing the official Filing Receipt, we noted an error in that the **foreign application information is missing and should read as --JAPAN 2003-0847743/26/2003--**. A copy of the **Declaration** is enclosed which indicates the correct information. We are enclosing a copy of the filing receipt with the corrections highlighted.

In the event that any fees are required in connection with this paper, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, KRATZ, QUINTOS,
HANSON & BROOKS, LLP


William L. Brooks

Attorney for Applicants
Reg. No. 34,129

WLB/bjb
Atty. Docket No. **040509**
Suite 1000
1725 K Street, N.W.
Washington, D.C. 20006
(202) 659-2930



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PATENT TRADEMARK OFFICE

Enclosures: Official Filing Receipt and Declaration



UNITED STATES PATENT AND TRADEMARK OFFICE

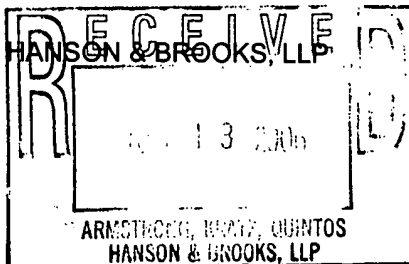


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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/517,765	02/03/2006	2812	1630	040509	12	18	6

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CONFIRMATION NO. 6791

FILING RECEIPT



OC000000019188213

Date Mailed: 06/12/2006

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Takashi Ozaki, Nakano-ku, JAPAN;
Kenichi Suzuki, Nakono-ku, JAPAN;

Assignment For Published Patent Application

HITACHI KOKUSAI ELECTRIC INC.,, TOKYO, JAPAN

Power of Attorney: The patent practitioners associated with Customer Number 23850.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP03/08097 06/26/2003

Foreign Applications

JAPAN 2002-187566 06/27/2002

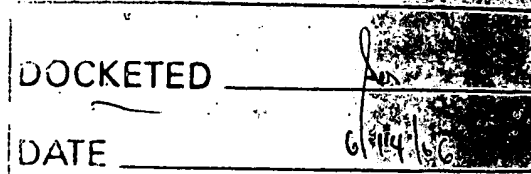
~~JAPAN 2003-084774 03/20/2003~~ -

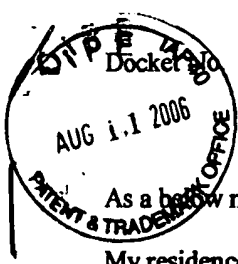
Projected Publication Date: 09/14/2006

Non-Publication Request: No

Early Publication Request: No

Title



**DECLARATION FOR U.S. PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**SUBSTRATE TREATING APPARATUS AND METHOD FOR MANUFACTURING
SEMICONDUCTOR DEVICE**

the specification of which is attached hereto unless the following is checked

☒ was filed on **DECEMBER 23, 2004** as United States Application Number or PCT International

Application Number **10/517,765** and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) – (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed.

Priority Claimed

(List prior foreign applications. See note A)

2002-187566 (Number)	Japan (Country)	27/6/2002 (Day/Month/Year Filed)
2003-084774 (Number)	Japan (Country)	26/3/2003 (Day/Month/Year Filed)
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)

☒ Yes ☐ No

☒ Yes ☐ No

☐ Yes ☐ No

☐ Yes ☐ No

(See note B)

☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(List prior U.S. Applications)

_____ (Application Serial No.)	_____ (Filing Date)
_____ (Application Serial No.)	_____ (Filing Date)
_____ (Application Serial No.)	_____ (Filing Date)

Status

☐ Patented ☐ Pending ☐ Abandoned

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